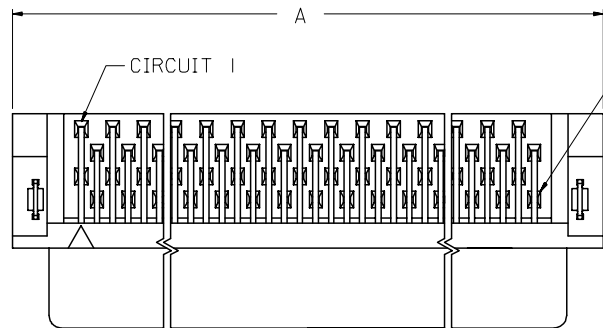
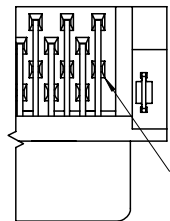
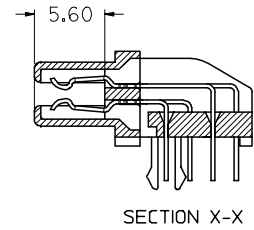
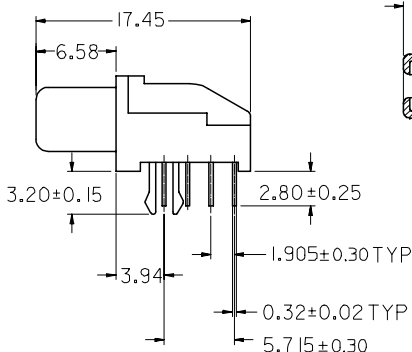
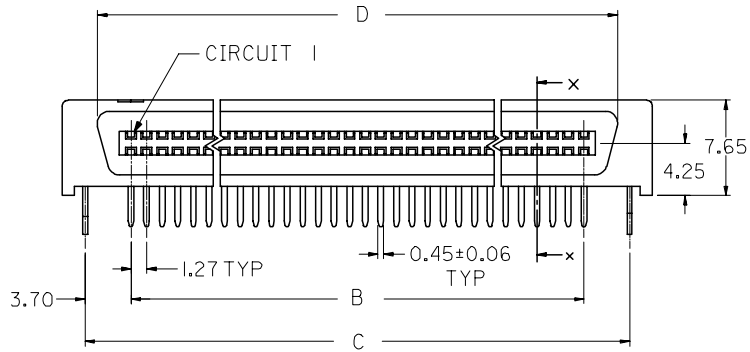
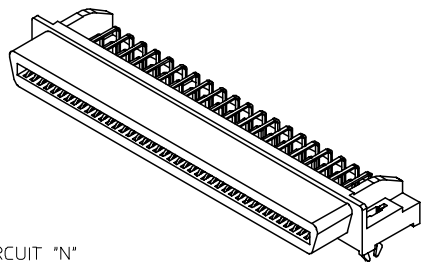




FOR CIRCUIT SIZES 68 AND 80 ONLY



FOR CIRCUIT SIZE 50 ONLY



NOTES:

1. MATERIAL: HOUSING -- HIGH TEMP. THERMOPLASTIC, UL94-V0
TERMINALS -- COPPER ALLOY
2. PLATING:
2A 0.75µM MIN. GOLD IN SELECTIVE CONTACT AREA AND
2.5µM MIN. TIN IN SOLDER TAIL AREA, BOTH
OVER 1.27µM MIN. NICKEL.
3. ASSEMBLY MATES WITH MOLEX P/N 71661-****.
4. RECOMMENDED P.C. BOARD THICKNESS IS 1.60MM.
5. PRODUCT SPEC. NO.: PS-87552-006
6. SEE TABLE ON SHEET 2 FOR ASSEMBLY PART NUMBERS.

REVISED	EC NO: S2008-0347	2007/11/12	DRWN:SKANG	2007/11/12	CHKD:ATSEE	2007/11/12	APPR:MLONG	2007/11/14
H3								

QUALITY SYMBOLS
▽=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
4 PLACES	± ---
3 PLACES	± ---
2 PLACES	± 0.3
1 PLACE	± ---
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
DSOH	1997/04/01
CHECKED BY	DATE
KCL ING	1997/05/06
APPROVED BY	DATE
SKTOH	1997/05/08
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
TITLE EBBI, 1.27MM PITCH RECEPTACLE, R/A		
molex MOLEX INCORPORATED		
DOCUMENT NO. SD-87552-007		SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

